

1. Features

- n Advanced trench process technology
- n High density cell design for ultra low on-resistance
- n Fully characterized avalanche voltage and current

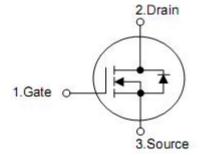
2. Features

- n 50A, 30V, R_{DS} (on) typ. = 6.5mΩ(typ.)@ V_{GS} = 10 V
- n Low gate charge
- n Low Crss
- n Fast switching
- n Improved dv/dt capability

3. Pin configuration



10-252



Pin	Function	
1	Gate	
2	Drain	
3	Source	



4. Ordering Information

Part Number	Package	Brand		
KIA50N03BD	TO-252	KIA		

5. Absolute maximum ratings

(T_C= 25°C, unless otherwise noted)

Symbol	Parameter	Value	Units
V _{DSS}	Drain-Source Voltage	30	V
I.	Drain Current -Continuous (T _C = 25 °C)	50	Α
l _D	-Continuous (T _C = 100 °C)	30	Α
I _{DM}	Drain Current -Pulsed	200	Α
V _{GSS}	Gate-Source Voltage	±20	V
E _{AS}	Single Pulsed Avalanche Energy (Note 1)	85	mJ
P _D	Power Dissipation (T _C = 25 °C)	60	W
	-Derate above 25 °C	0.5	W/ºC
T _J ,T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C

6. Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case	1.8	°C /W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	°C /W



7. Electrical characteristics

(Tc= 25°C, unless otherwise noted)

	(1c= 25°C, unless otherwise noted)					
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	Off Characteristics					
B _{VDSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \text{ uA}$	30			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} = 30 V, V _{GS} = 0 V			1	uA
I _{GSS}	Gate- Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Char	acteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \text{ uA}$	1.0	1.6	3.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 15 A		6.5	9.9	mΩ
R _G	Gate Resistance	f = 1.0 MHz		5.0		Ω
Dynamic	Characteristics					
C _{iss}	Input Capacitance			1200		pF
Coss	Output Capacitance	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		150		pF
Crss	Reverse Transfer Capacitance	1 = 1.0 WH 12		115		pF
	Switchi	ing Characteristics				
t _{d(on)}	Turn-On Delay Time			4.6		ns
tr	Turn-On Rise Time	$V_{DD} = 20 \text{ V,V}_{GS}=10 \text{ V,}$ $I_{D} = 15 \text{ A, R}_{G} = 6 \Omega$ (Note2.3)		35		ns
t _{d(off)}	Turn-Off Delay Time			40		ns
t _f	Turn-Off Fall Time			16		ns
Qg	Total Gate Charge			25		nC
Q _{gs}	Gate-Source Charge	$V_{DD} = 24 \text{ V, } I_{D} = 15 \text{A,}$ $V_{GS} = 10 \text{ V}^{\text{(Note 2,3)}}$		5.0		nC
Q_{gd}	Gate-Drain Charge			5.5		nC
Drain-Sc	urce Diode Characteristics and Maximu	ım Ratings				
Is	Continuous Source Current	Integral Reverse P-N Junction Diode in the MOSFET			50	Α
I _{SM}	Pulsed Source Current				200	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S =15 A			1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 15 \text{ A,}$ $dI_{F} / dt = 100 \text{ A/us}^{\text{(Note 2)}}$		12.5		ns
Qrr	Reverse Recovery Charge			0.005		uC
		•				

Notes:

- 1. L = 0.5mH, V_{DD} = 15V, V_{GS} = 10V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C
- 2. Pulse Test : Pulse width ≤ 300us, Duty cycle ≤ 2%
- 3. Essentially independent of operating temperature



On - Resistance - R_{DS(ON)} (mΩ)

8. Typical Characteristics

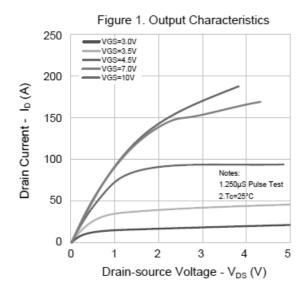


Figure 3. On-resistance vs. Drain Current

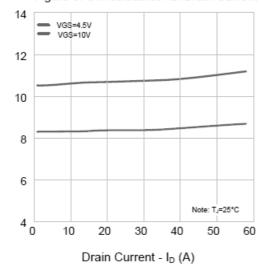


Figure 5. Capacitance Characteristics

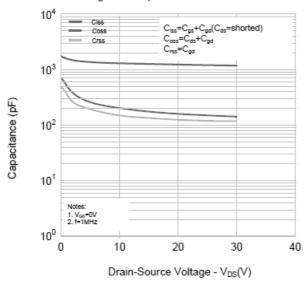


Figure 2. Transfer Characteristics

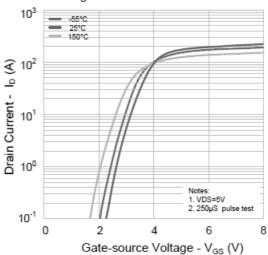


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

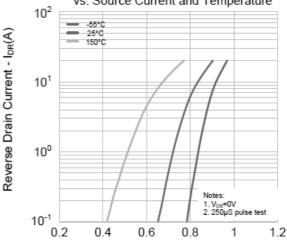
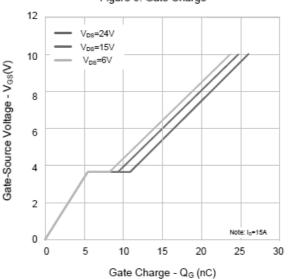
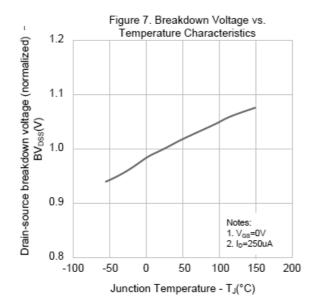


Figure 6. Gate Charge

Source-Drain Voltage - V_{SD} (V)







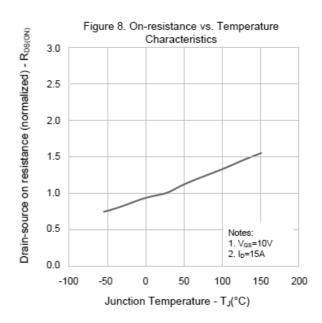


Figure 9. Max. Safe Operating Area

